# **Electronic Acknowledgement Receipt** FES ID: 1047029 Application Number: 10673686 Confirmation Number: 1295 Mounting spring elements on semiconductor devices, and wafer-level Title of Invention: testing methodology First Named Inventor: Benjamin N. Eldridge Customer Number: 50905 Filer: N. Kenneth Burraston/Erin Cowles Filer Authorized By: N. Kenneth Burraston Attorney Docket Number: P7D7C2-US Receipt Date: 15-MAY-2006 Filing Date: 29-SEP-2003 Time Stamp: 13:09:28 Application Type: Utility International Application Number:

### Payment information:

Submitted with Payment no

## File Listing:

Documen Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		P7D7C2US.pdf	289336	yes	6

	Multipart Description			
	Doc Desc	Start	End	
	Petition for review by the Technology Center SPRE.	1	5	
	Miscellaneous Incoming Letter	6	6	
Warnings:				

Warnings

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### New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

#### National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.